

FOR IMMEDIATE RELEASE

STATS ChipPAC Announces Resignation of Chief Operating Officer

Singapore – 22 September 2014 – STATS ChipPAC Ltd. (“STATS ChipPAC” or the “Company” – SGX-ST: STATSchP), a leading provider of advanced semiconductor packaging and test services, announced today that Mr. Wan Choong Hoe has resigned from his position as Executive Vice President and Chief Operating Officer effective 30 September 2014 to pursue personal interests.

“We thank Choong Hoe for his invaluable contributions and wish him success in his future endeavours,” said Mr. Tan Lay Koon, President and Chief Executive Officer, STATS ChipPAC.

Mr. Tan Lay Koon will serve as acting Chief Operating Officer until the Company identifies a suitable candidate.

About STATS ChipPAC Ltd.

STATS ChipPAC Ltd. (SGX-ST Code: S24) is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com. Information contained in this website does not constitute a part of this release.

Investor Relations Contact:

Tham Kah Locke
Vice President of Corporate Finance
Tel: (65) 6824 7788, Fax: (65) 6720 7826
email: kahlocke.tham@statschippac.com

Media Contact:

Lisa Lavin
Deputy Director of Marketing Communications
Tel: (208) 867-9859
email: lisa.lavin@statschippac.com



STATS ChipPAC Ltd.

Company Registration No.: 199407932D

Headquarters: 10 Ang Mo Kio Street 65, #05-17/20 Techpoint,
Singapore 569059

www.statschippac.com